



Koh Young Showcases Advanced Dimensional Metrology and Inspection Solutions for Semiconductor and Wafer-Level Packaging at SEMICON West

Seoul, Korea – Koh Young Technology, the industry leader in True 3D™ measurement-based dimensional metrology and inspection solutions, will present its latest advancements for semiconductor and advanced packaging applications at SEMICON West 2025 in Booth 5949. The show will take place in its new venue at the Phoenix Convention Center from October 7–9, 2025 in Phoenix, Arizona.

With nearly 25,000 systems installed at more than 3,900 manufacturing sites, Koh Young set the standard in automated optical inspection for the electronics manufacturing industry. Building on that foundation, the company expanded into semiconductor manufacturing with higher-resolution optics, advanced measurement algorithms, and solutions engineered for metrology and inspection of wafer-level packages (WLP), system-in-package (SiP), and ultra-high-density interconnect applications.

As an exhibitor, Koh Young will highlight how its AI-powered metrology and inspection solutions help manufacturers meet the exacting demands of advanced packaging and semiconductor processes. From wafer-level to SiP, Koh Young technology delivers accurate, repeatable data to enable smarter process control, drive higher yields, and support zero-defect initiatives.

Proven Platforms for Advanced Packaging Metrology

Koh Young's Meister Series is purpose-built for advanced packaging, including SiP, WLP, and die-stacking metrology. These systems provide ultra-high-resolution 2D/3D measurement to manage features and tolerances in next-generation designs. Complementing the Meister Series, the ZenStar delivers wafer-level dimensional metrology to detect and quantify critical parameters at the earliest stage, ensuring only known-good components advance. Together, these platforms help manufacturers maintain tight process windows, improve yield, and reduce costly rework.

"We are excited about the opportunities SEMICON West brings this year in Phoenix," said Joel Scutchfield, General Manager of Koh Young America. "The region has long been a center for semiconductor manufacturing, and the recent wave of investment and expansion has only strengthened its position as a hotbed for advanced packaging and innovation. We see tremendous potential for Koh Young to help manufacturers here solve their most pressing challenges. Our mission is to deliver meaningful process insights that improve yield, reduce risk, and give our customers a competitive edge. This show is the perfect forum to collaborate and share how our metrology and inspection solutions can make that vision a reality."



For more information about Koh Young's semiconductor-focused dimensional metrology and inspection systems, visit us at Booth 5949 during SEMICON West 2025 or online at www.kohyoung.com.

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About Koh Young Technology, Inc.

Founded in 2002, Koh Young Technology transformed the inspection market with the industry's first 3D Solder Paste Inspection (SPI) system using patented dual-projection Moiré technology. Today, Koh Young is the global leader in True3D™ measurement-based SPI and Automated Optical Inspection (AOI) solutions for electronics manufacturing. Building on its core True3D™ technology, Koh Young has expanded its capabilities to address complex inspection challenges, including machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packaging. Through continuous innovation and a customer-focused R&D approach, the company has earned the trust of over 3,800 customers worldwide and maintains the dominant global market share with nearly 25,000 systems installed. Headquartered in Korea with regional offices across the globe, Koh Young provides local sales and support to stay close to its markets and growing user base. Electronics manufacturers around the world rely on Koh Young to deliver reliable inspection, actionable process insight, and a pathway to a smarter factory. Learn more at www.kohyoung.com.